Shoulder 好达

SHOULDER ELECTRONICS CO., LTD.

CERAMIC RESONATOR Data Sheet

PRODUCT 产品: CERAMIC RESONATOR

MODEL NO 型 号: ZTACC....MG

PREPARED 编 制: Fengyu

CHECKED 审 核: York

APPROVED 批 准:

DATE 日期: 2007-01-25

1. Scope

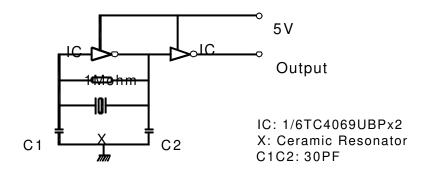
The specification is fit for ceramic resonator 1.84-8.00MHz.

2. Part Number: ZTACC .. MG

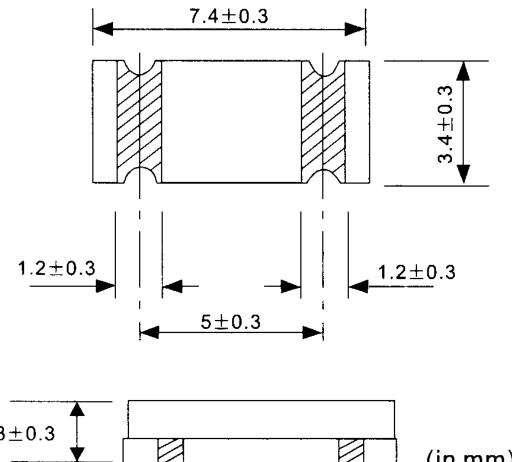
3. Electrical Characteristics

No.	ltem	Characteristics				
3-1	Oscillate Frequency (MHz)	1.84-8.00				
3.2	Frequency Tolerance max	±0.5%				
3.3	Resonant Impedance $\max{(\Omega)}$	100				
3.4	Built – in Capacitance (PF)					
3.5	Insulate Resistance min (M Ω)	100				
3.6	Withstanding Voltage D.C (V)	100 (max 5 sec)				
3.7	Voltage (1) D.C Voltage max (V) (2) Input Voltage max (V)	6 15Vp-p				
3.8	Temp characteristics of Oscillate frequency max	±0.3%				
3.9	Operating Temp Range (℃)	-20 ~ +80				
3.10	Storage Temp (℃)	-55 ~ +85				

4. Test Circuit



5. Dimension



1.8 ± 0.3 (in mm)

6. Physical and Environmental Characteristics

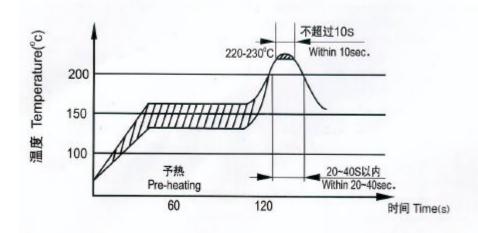
No	Item	Condition of Test	Performance Requirements			
6.1	Humidity	Keep the resonator at 40±2℃ and 90-95% RH for 96 ± 4 hours. Then release the resonator into the room condition for 1 hour prior to the measurement.	It shall fulfill the specifications in Table 1.			
6.2	Vibration	Subject the resonator to vibration for 2 hours each in x,y and z axis with the amplitude of 1.5mm, the frequency shall be varied uniformly between the limits of 10-55Hz	It shall fulfill the specifications in Table 1.			
6.3	Mechanical Shock	Drop the resonator randomly onto a concrete floor from the height of 100 cm 3 times.	It shall fulfill the specifications in Table 1.			
6.4	Soldering Test	Passed through the re-flow oven under the following condition and left at room temperature for 1 hour before measurement.	It shall fulfill the specifications in Table 1.			

		Temperature at surface of the substrate	Time			
		Preheat 150±5℃ Peak 240±5	60±10 sec. 10±3 sec.			
		r				
6.5	Solder Ability	Dip the resonator solder bath at 230±	More than 95% of the terminal surface shall be covered.			
6.6	High Temperature Exposure	Subject the resona ±4 hours. Then r into the room condito the measurement	It shall fulfill the specifications in Table 1.			
6.7	Low Temperature	Subject the resonat ±4 hours. Then r into the room condito the measurement	It shall fulfill the specifications in Table 1.			
6.8	Temperature Cycling	Subject the resonant minutes followed bound of 85°C for 30 m repeated 5 times with 15 second at the hour prior to the me	It shall fulfill the specifications in Table 1.			

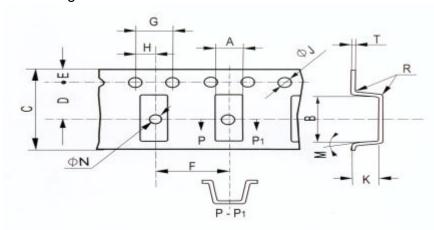
TABLE1

Item	Specification				
Oscillation Frequency Change	∆F/Fo≤0.3% max				
Resonant Impedance	∆Ro≤±10 Ohm				

7. RECOMMENDED REFLOW SOLDERING STANDARD CONDITIONS



8. Packing



Tape Dimension (mm)

	Α	В	С	D	E	F	G	Н	Ø	ØN	M	R	K	Т
	±0.2	±0.2	±0.3	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	max	max	±0.2	±0.1
MG	3.8	7.8	16.0	7.5									2.1	
MT	5.0	4.4	12.0	5.5	1.75	8.0	4.0	2.0	1.5	1.6	10"	0.3	1.8	0.3
MX	3.4	4.0	12.0	5.5									1.3	

Standard Package: 4Kpcs / reel